



Tech Talk

# “Why Pure”



# HPC/EDA & Pure Storage

**Bikash Roy Choudhury**

Director, HPC/EDA/DevOps Solutions- Pure Storage

# Chip and Software Design Headlines & Opportunities

- Faster Time to Result
- Lower Costs
- Maximize Competitiveness
- Reduce Dev Cycle Times
- Scale & Grow as Business Dictates
- Improve Quality

## Third Quarter Sales Hit By Delivery Delays

**Micron Is First to Deliver 3D Flash Chips With More Than 200 Layers** > 232-layer NAND makes tiny 2-terabyte products that deliver data 50 percent faster

HOME · COMPUTING · NEWS

**Intel has 500 bugs to fix in its next supercomputer chips**

## Meta tells employees it will freeze hiring and restructure some teams in cost cutting effort

**Micron Is First to Deliver 3D Flash Chips With More Than 200 Layers** > 232-layer NAND makes tiny 2-terabyte products that deliver data 50 percent faster

**3D-Stacked CMOS Takes Moore's Law to New Heights** > When transistors can't get any smaller, the only direction is up

## The Chip Shortage, Giant Chips, and the Future of Moore's Law > IEEE Spectrum's biggest semiconductor headlines of 2021

**U.S. Passes Landmark Act to Fund Semiconductor Manufacturing** > CHIPS and Science Act of 2022 provides billions for new fabs and other incentives

**The First High-Yield, Sub-Penny Plastic Processor** > It took a major redesign for cheap flexible chips to reach their promise

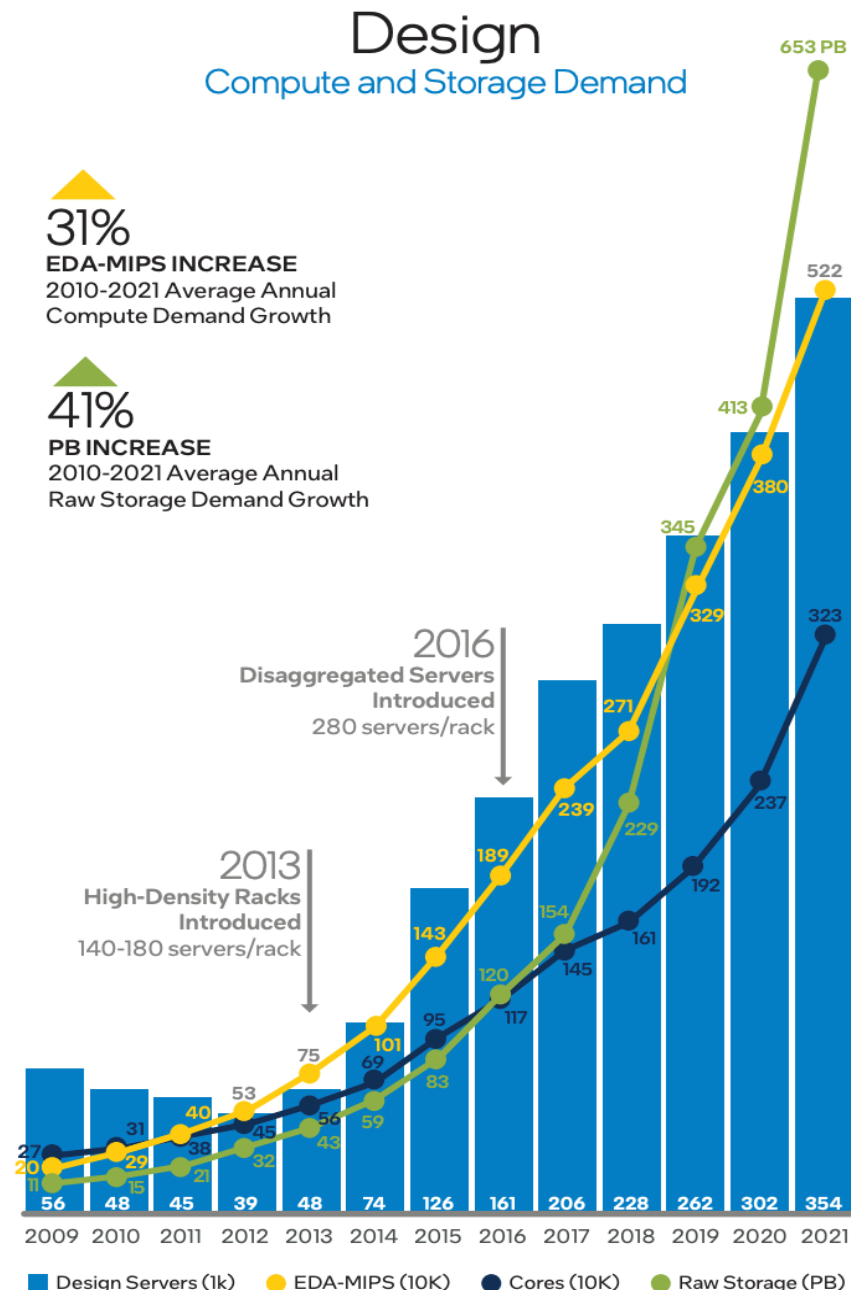
**Nvidia's Next GPU Shows That Transformers Are Transforming AI** > The neural network behind big language processors is creeping into other corners of AI

**Autodesk to Launch Construction-Specific Cloud Collaboration Platform**

# EDA Design Trends

- Increased compute requirements on-demand
  - Faster job completion times
  - Reduce compute per Watt
- Massive data growth during chip design
  - Sub 10nm designs generate more data
  - Silicon sizes dropping to <20Å with multi-die
- Lots of consolidation in the industry
  - Increased mixed workloads and environments
  - Shift towards AI-designed commercial tape-outs
- Transition into Hybrid Cloud for design workloads
  - Compute, Compute and more Compute for complex designs
  - Scalable performance and data continuity on-premises/Cloud

<https://www.intel.com/content/www/us/en/it-management/intel-it-best-practices/data-center-strategy-paper.html>  
<https://www.intel.com/content/dam/www/central-libraries/us/en/documents/semiconductors-and-intel-introduction.pdf>



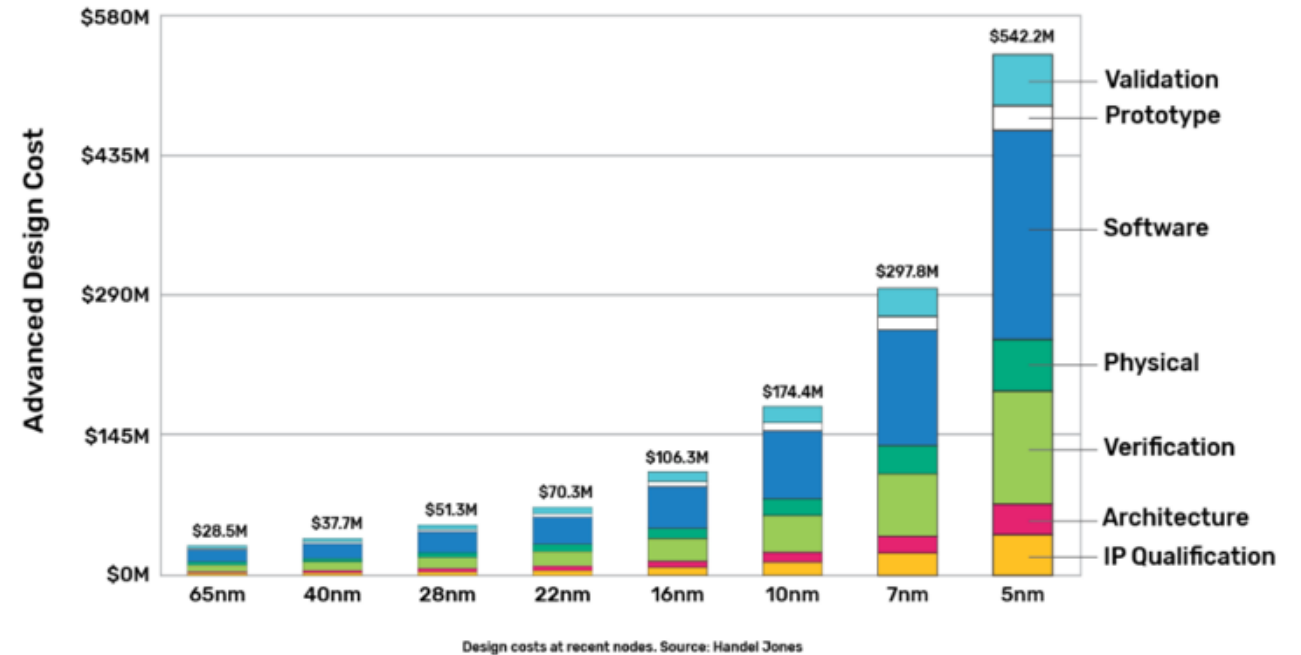
Pure Storage Tech Talk "Why Pure"



# Factors driving Chip Design Costs

## Challenges

- Design complexity w/higher EDA Tool license Costs
- Slow design turnaround time impacting TTM
- Long running jobs with limited scalability
- Slow infrastructure with limited scalability - compute, network, storage



Source: <https://www.chipestimate.com/How-to-address-SiP-challenges-with-EDA-tools-and-IP/Cadence/Technical-Article/2020/09/08>

# EDA Businesses Needs



## Scale more cores in compute farm for incremental growth

Enable growth with headroom and non-disruptive upgrades



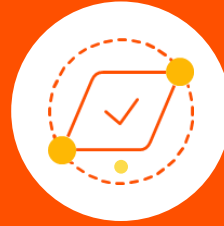
## Accelerate SW Delivery Pipeline (Decrease TTM)

Improve developer productivity with increased software quality



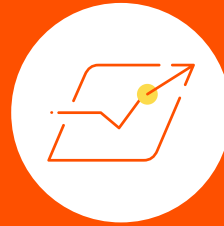
## Simplify Storage Management

Monitor and reporting of EDA Infra end-points



## Deliver designs faster with reduced job completion times.

Keep your pipeline of designs flowing, optimize (or lower) EDA Tool License Costs.



## Provide scalable and efficient performance

Scale storage and compute independently (disaggregated) and reduce data center footprint



## Mobilize data for hybrid cloud

Enable array/host based data mobility and build enterprise hybrid cloud solutions with no compromises



# EDA Workflow: Potential Bottlenecks

## COMPUTE

(Scale on-demand - Flexibility to extend into cloud)

## SCHEDULER

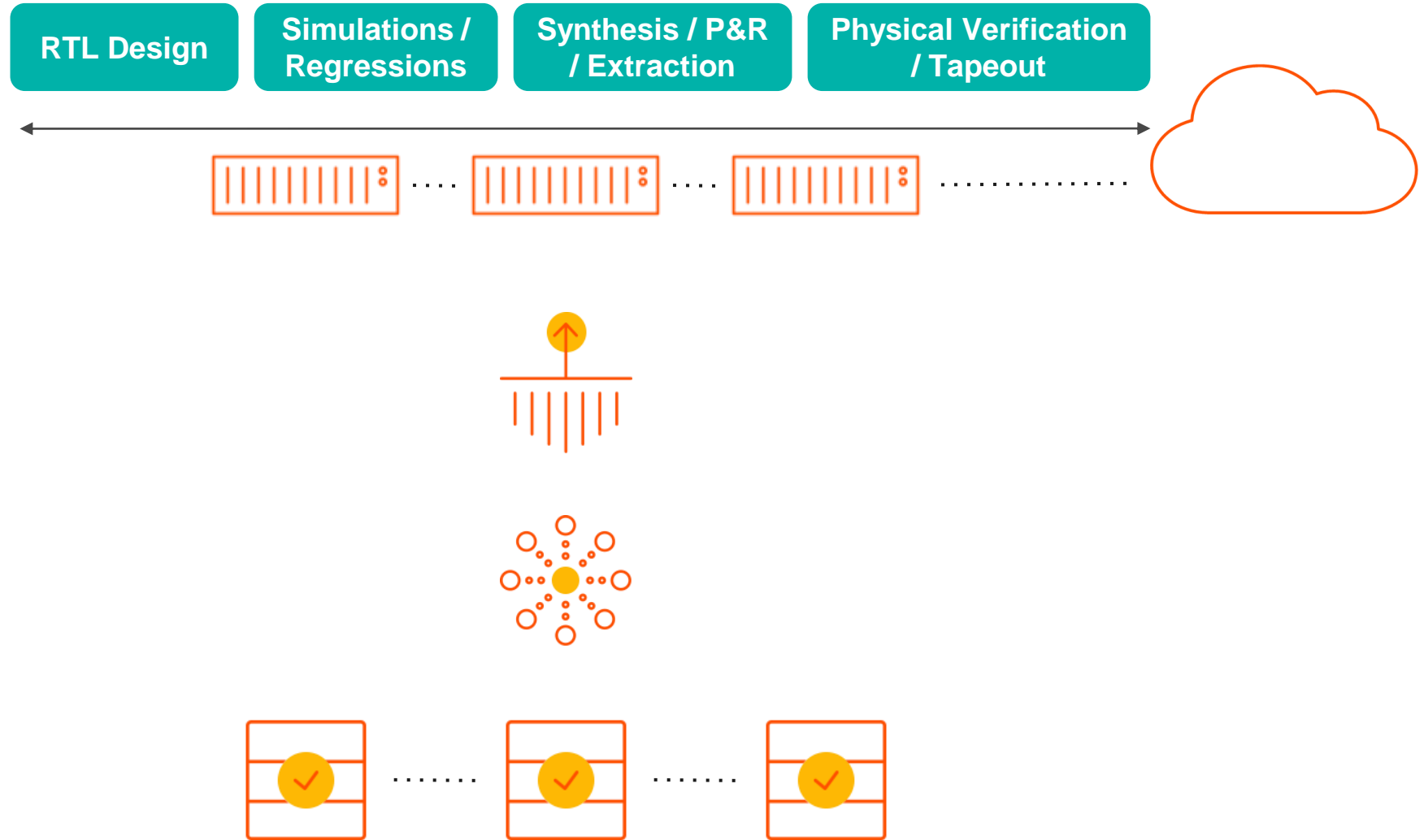
(24/7 Queue - Resubmit failed jobs - not storage aware)

## NETWORK

(IO bottleneck/ Saturating network from compute hosts to Storage)

## STORAGE

(Concurrent Data access at scale - variable/competing workloads)



# Accelerate Chip Design Workflows and Tools



# Shorten Chip Design Cycles in EDA

**Major EDA Provider**

>10X Build run-time Improvement

**Top 10 Semiconductor**

Enable > 200M more simulations every year

**Social Media AI**

~50 GB/s throughput for deep learning

**Top 10 Semiconductor**

Reached 70 GB/s and 2.3 million IOPS

**Major EDA Provider**

40% Questa regression runtime improvement

**Top 10 Semiconductor**

60%+ PrimeTime runtime improvement

**Top EDA Provider**

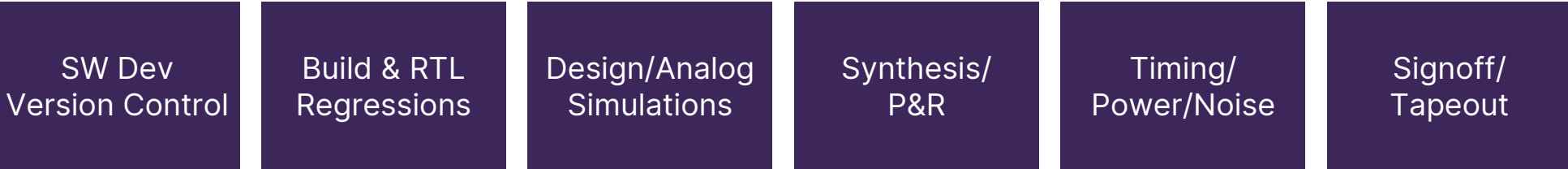
Achieved 1.4 million IOPs during simulation phase

**Various EDA Companies**

RapidFile Toolkit results in up to 60x speed up of millions of file operations

# Consolidate Semiconductor Workloads to Accelerate Chip Design Workflows

## CHIP DESIGN WORKFLOW



## COMPUTE LAYER – ON PREMISES / CLOUD



## JOB SCHEDULER – PBS/LSF/UNIVA

## CONSOLIDATED WORKLOADS ON FLASHBLADE



## NFS



Parallel Access  
Tested in > 500K  
Core Environments

Metadata  
>30 Million IOPS

Bandwidth  
>300 GB/s

Fast Delete  
>50K files/sec

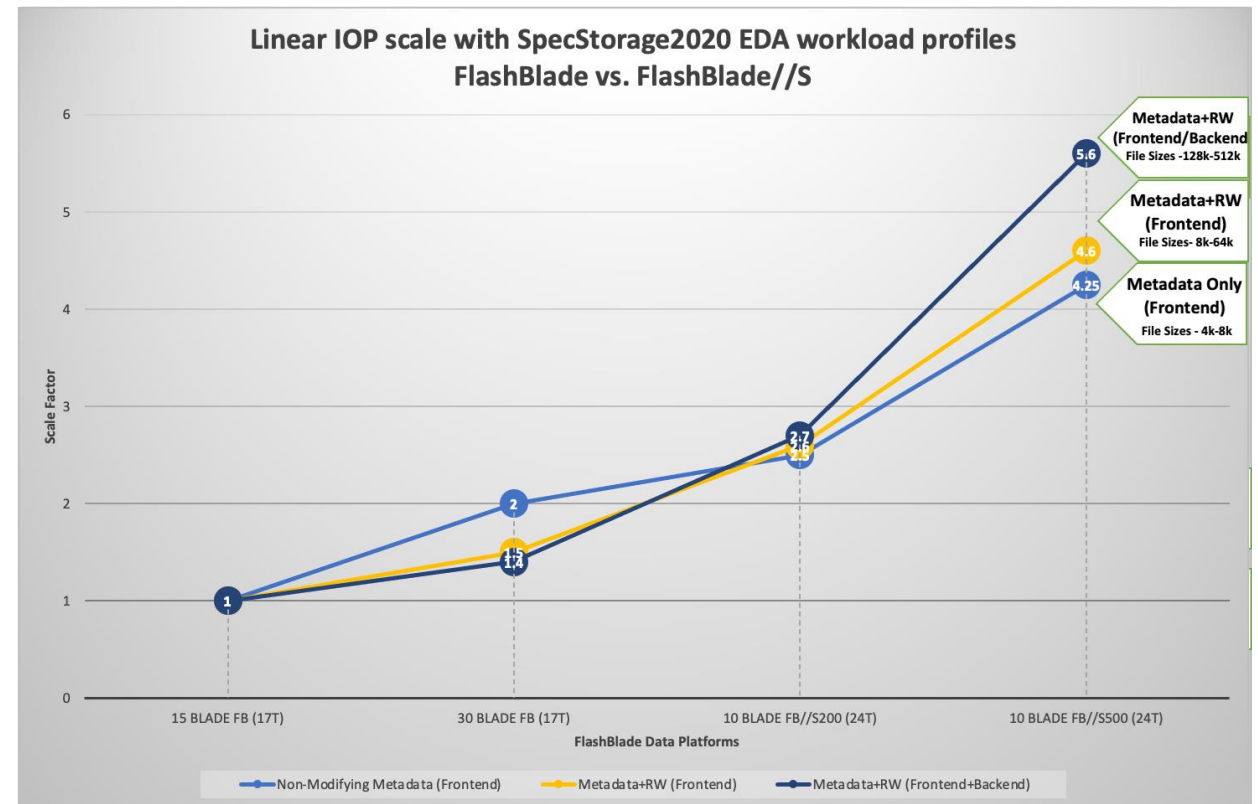
High File Count  
 $2^{56}$

Capacity  
19+ PB (2:1)

# Reduce Logical Verification time in EDA Process by 50%

FlashBlade vs. FlashBlade//S over NFSv3

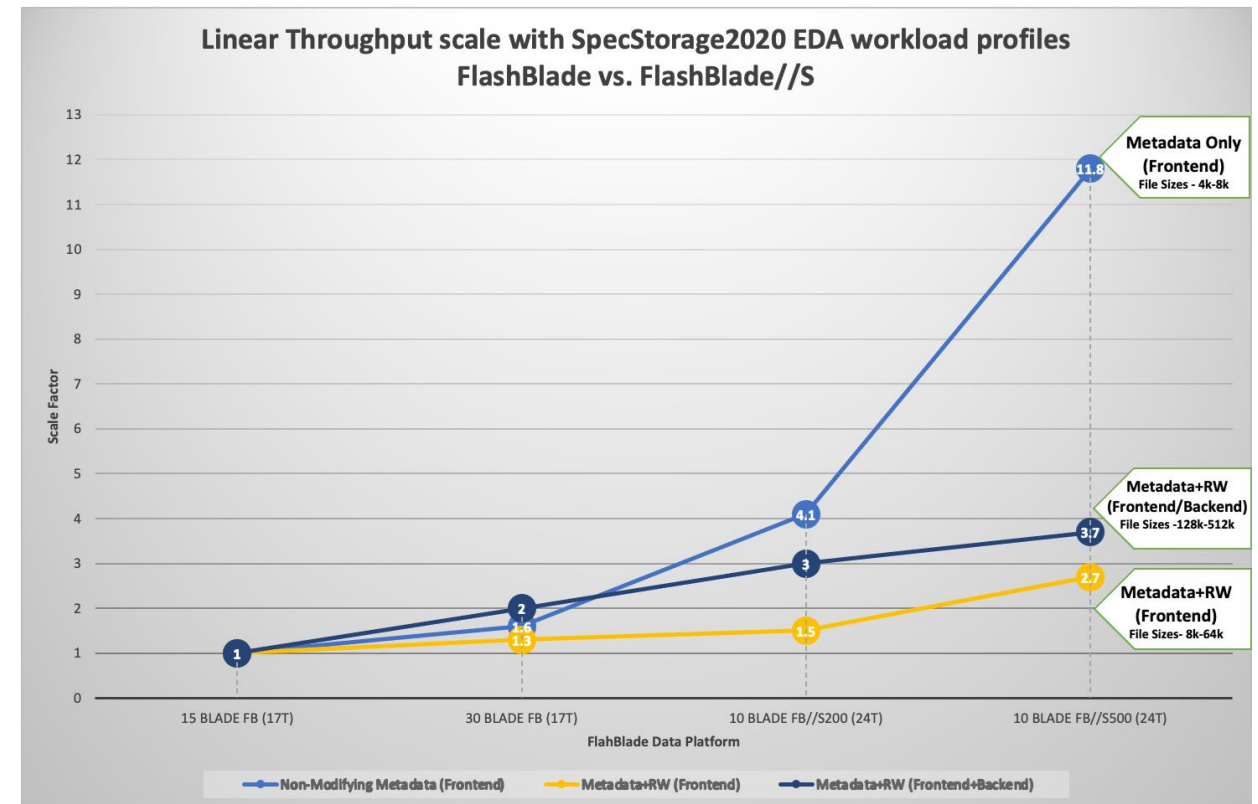
- Increase IOPs for metadata only workloads by > 2.5x
- Reduce overall latency by 50%
- Scale more compute cores by 50%
- Increase data reduction by > 30%



# Reduce Regression Time During Tapeout by 50%

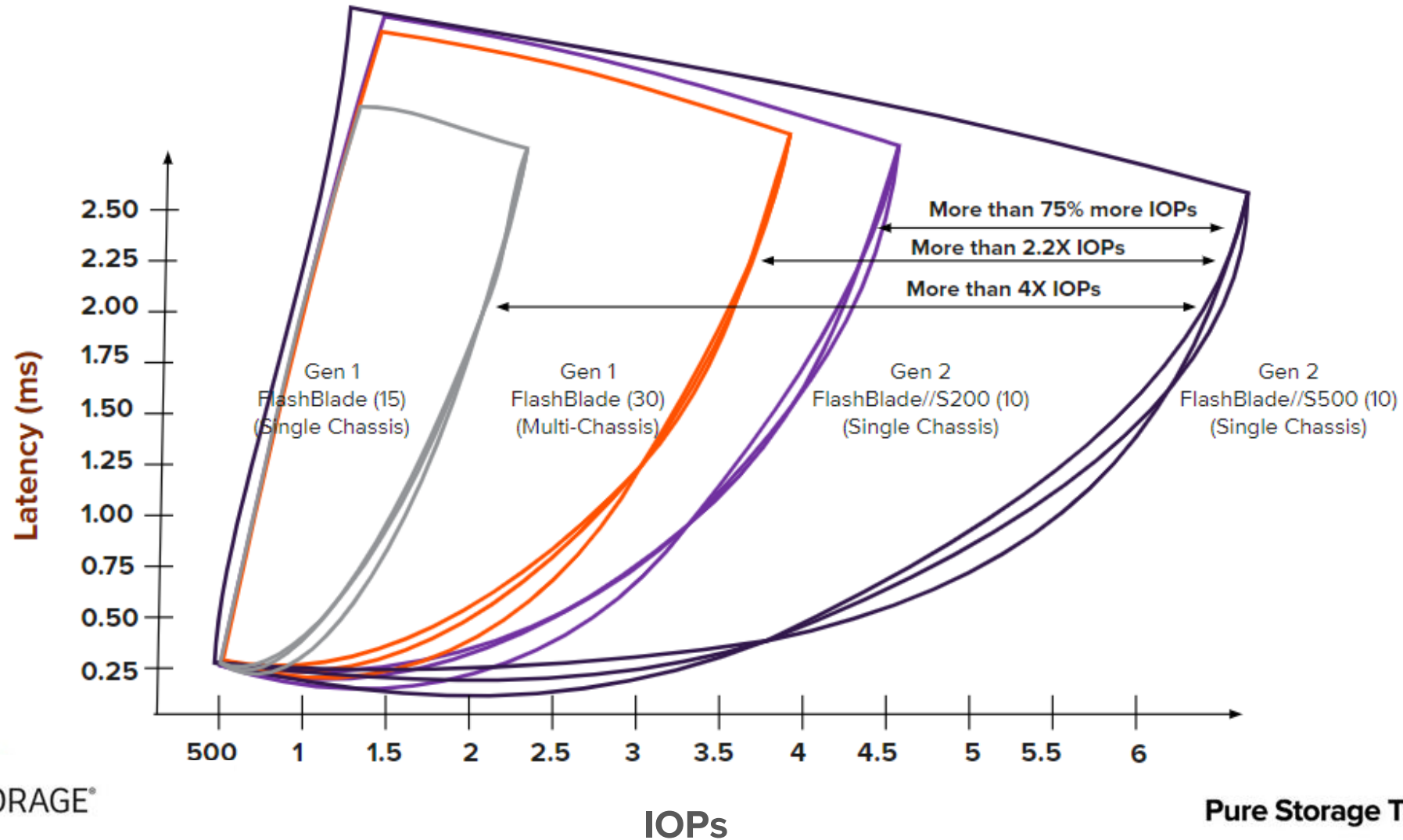
FlashBlade vs. FlashBlade//S over NFSv3

- Increase bandwidth by 75%
- Reduce write latency by 60%
- Scale compute cores up to 50% more



# EDA Generational Performance Better by 4X

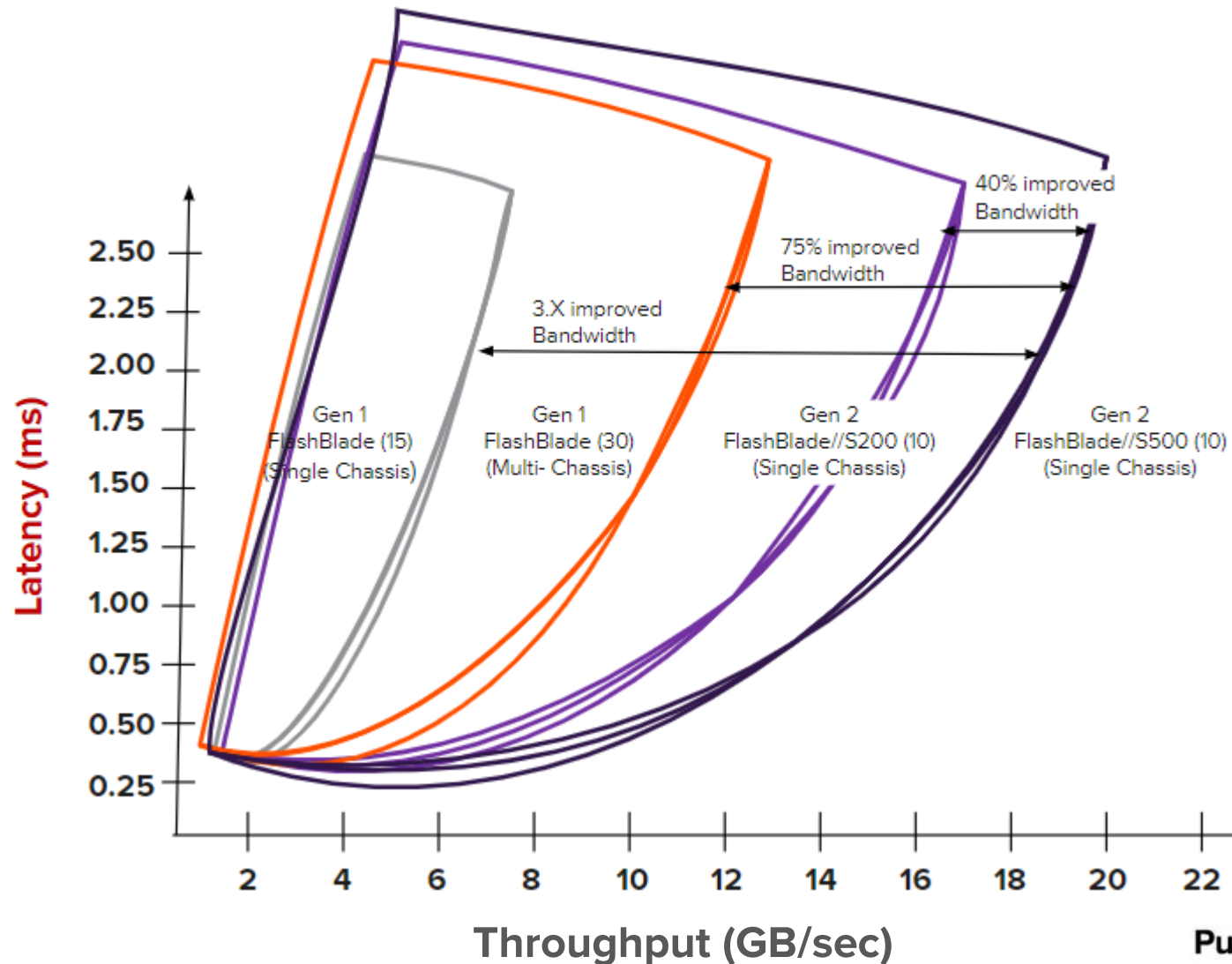
FlashBlade//S: IOPS vs Latency



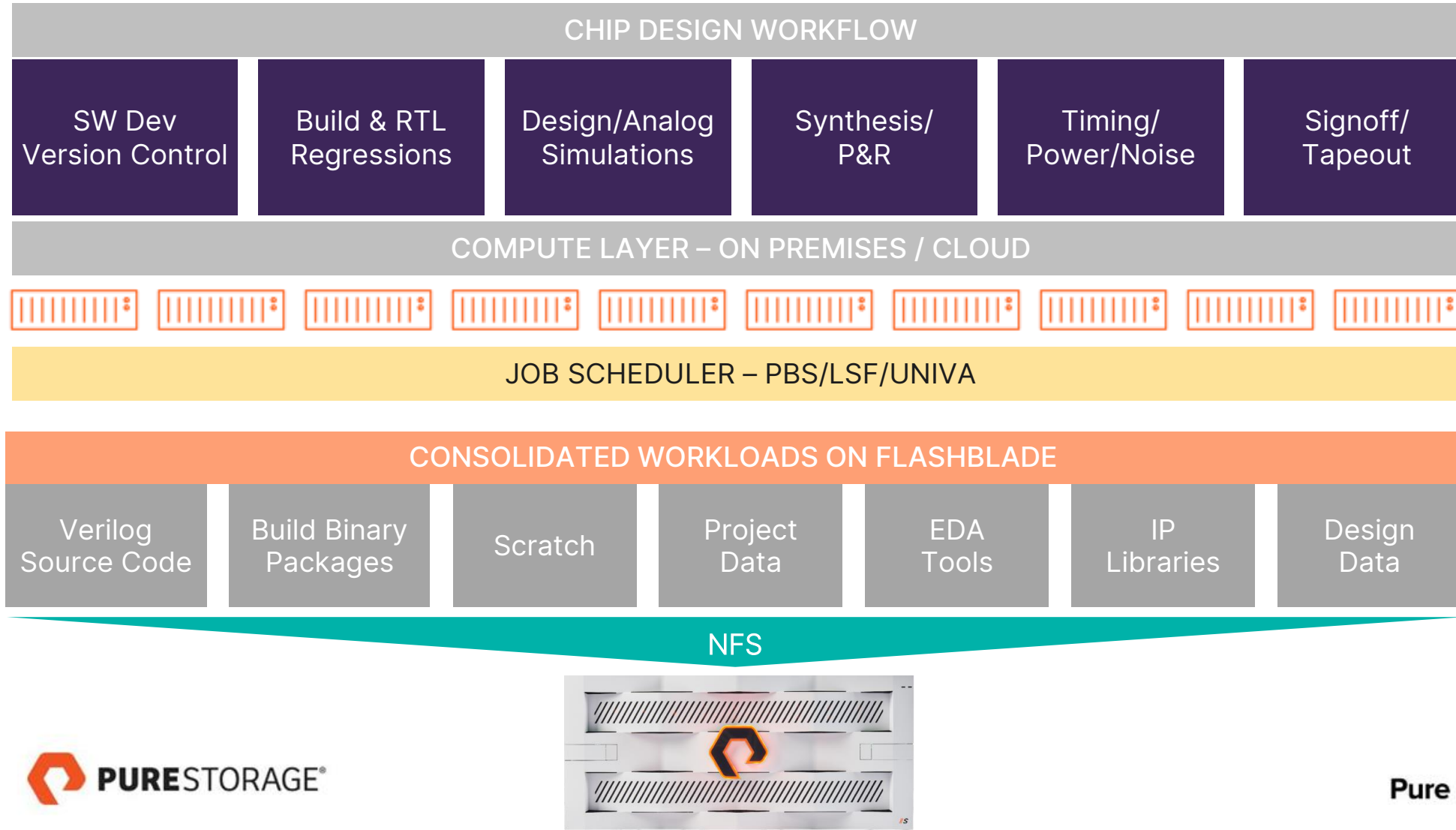


# EDA Generational Performance Up to 3X Better

FlashBlade//S Bandwidth vs Latency



# Consolidate Semiconductor Design Workflows with FlashBlade//S

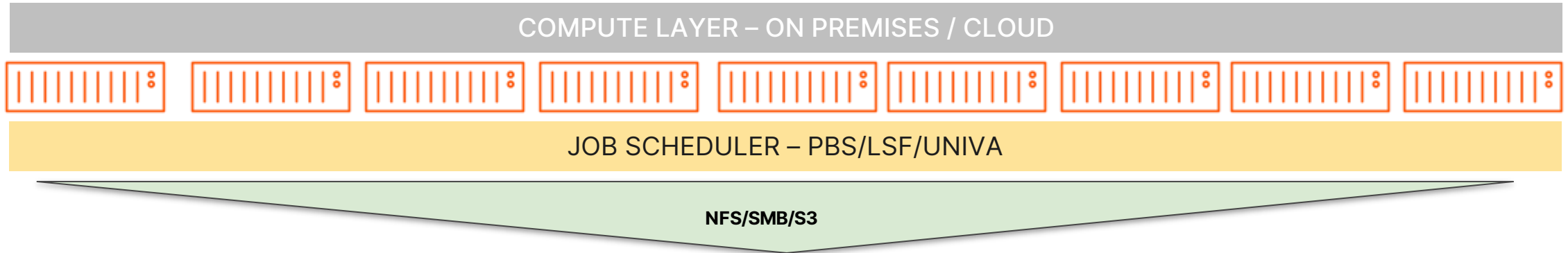


## Post-production challenges

- Unused design data on Flash Storage
- Restricting onboarding new projects
- Inefficient capacity & energy usage
- Reduced ROI

# Data Lifecycle with FB//S and FB//E

Array and host based data mobility



**Active Design Projects**



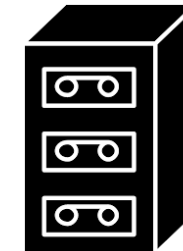
Scalable Performance

**Content Repository**



Scalable Capacity

**Frozen data**



Tape Library

# Native Array Level Data Mobility from FB//S to FB//E

Snapshot based Bi-directional file system Array level replication



NFS/SMB/S3

Active Project Data



FlashBlade//S

Bi-directional  
array level  
file system  
replication

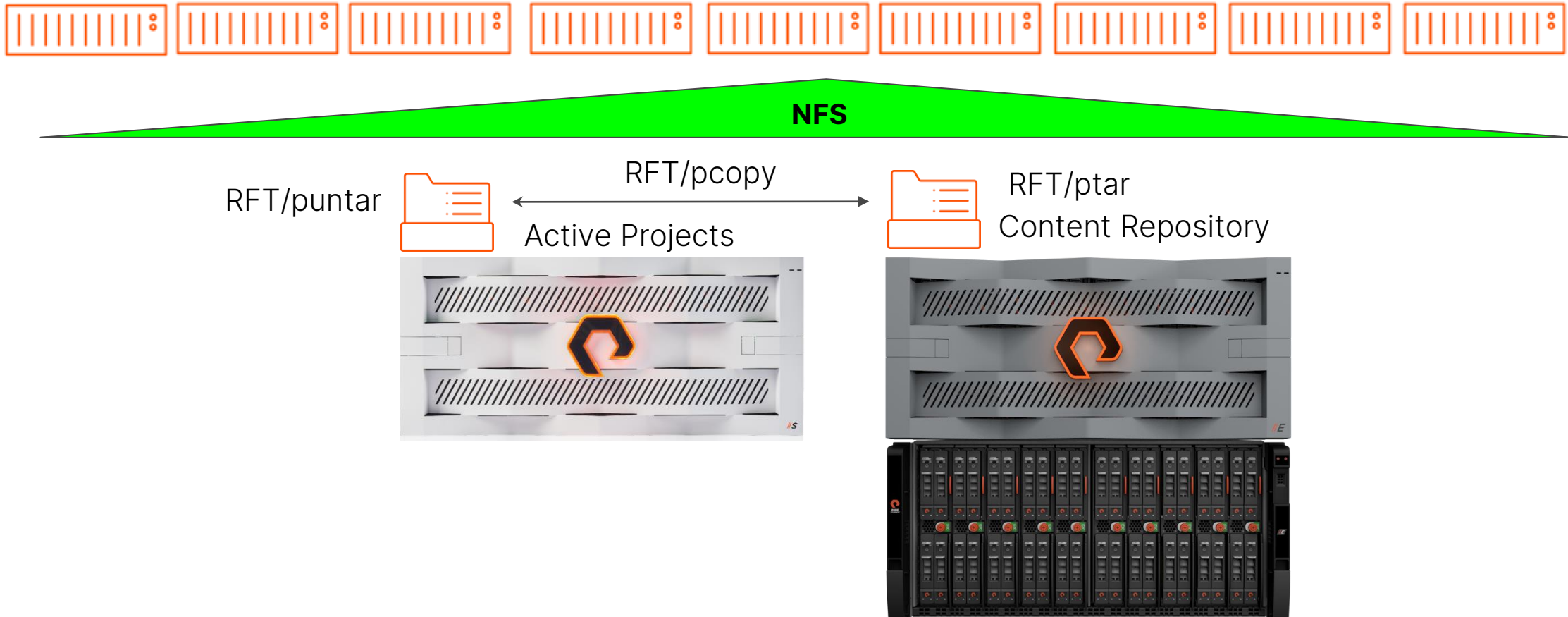
Content Repository



FlashBlade//E

# Host based select Data Mobility with Rapid File Toolkit (RFT)

Using RFT/ptar/pcopy to move select files/directories from //S to //E





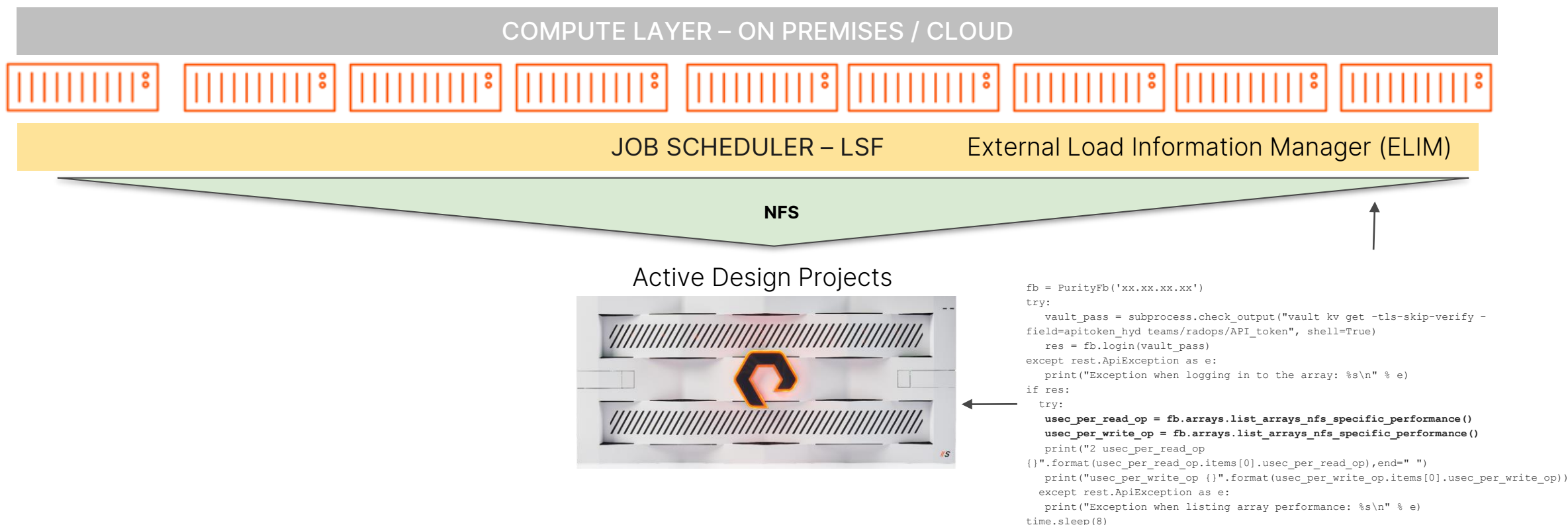
# Data Lifecycle for Chip design workloads

Benefits with Pure Storage FB//S and FB//E

- Active project data can move to archive storage after the project is over.
  - New projects can start after old data is moved to FB//E and the source file systems are removed on FB//S.
  - Common tools and libraries continue to move the changes to FB//E until all the collaborative projects are over.
- Design data, tools and libraries can be moved to FB//E at the array and host level after project completion
  - Snapshot based bidirectional file system replication allows to move the entire filesystem to FB//E.
  - Host based tool like RFT provides the ability to move select files and directories to FB//E faster.
- Chip design projects and data can be archived on all flash arrays for better cost efficiency
  - Data continuity with FB//E allows data access over standard file and object protocols
  - The FB//E is not designed for scalable performance; performance is limited

# Smart job scheduling with LSF/ELIM using FB/APIs

Benefits with Pure Storage FB//S and FB//E



- Control job submission in the queue when the storage is busy.
- Optimizes EDA tool license costs by limiting job submission to the queue beyond a threshold array latency value.
- Integrating FB/APIs with ELIM smoothens the job submission to the queue and preemptively identifies storage saturation.

# EDA Workflow Solutions

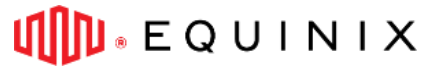
Pure Storage Portfolio offerings for semiconductor design and manufacturing organizations

Performance and Capacity @ Scale

PERFORCE  
SYNOPSYS®



Cloud



Data Mobility



Observability



Pure Storage Tech Talk “Why Pure”

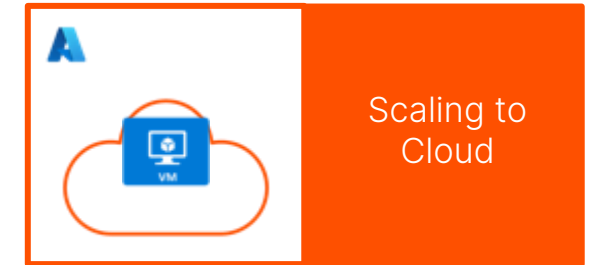
# Connected Cloud Software Dev & EDA Workflows

- Improve Engineering productivity
- Scalable performance and capacity
- Cost efficiency with improved Data reduction ratio
- Faster data recovery from failures
- Optimizing EDA tool license costs
- Data security and sovereignty with Hybrid Cloud



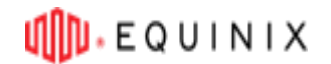
- Faster Software Delivery
- Accelerate design verification
- Managed EDA workflows

## On Premises



- Cloud bursting for EDA workflows

## Hybrid Cloud



Pure Storage Tech Talk “Why Pure”

# Thank You!

홈페이지 : [www.purestorage.com/kr](http://www.purestorage.com/kr)

페이스북 : [www.facebook.com/purestoragekorea](http://www.facebook.com/purestoragekorea)

블로그 : [www.blog.naver.com/purestorage\\_korea](http://www.blog.naver.com/purestorage_korea)

유튜브 : [www.youtube.com/@PureStoragekr](http://www.youtube.com/@PureStoragekr)





Uncomplicate Data Storage, Forever